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VDE/VDI-Society Microelectronics, Microsystems- and Precision Engineering (GMM)

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In cooperation with:

UBC Microelectronics

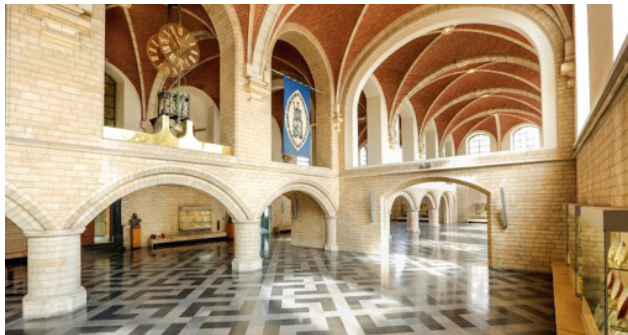
Dr. Uwe Behringer
EMLC 2022 Conference Chair

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Venue: Catholic University, Leuven, Belgium



KU Leuven, Belgium (© KU Leuven)



Jubilee Hall for Poster Session and Exhibition (© KU Leuven)

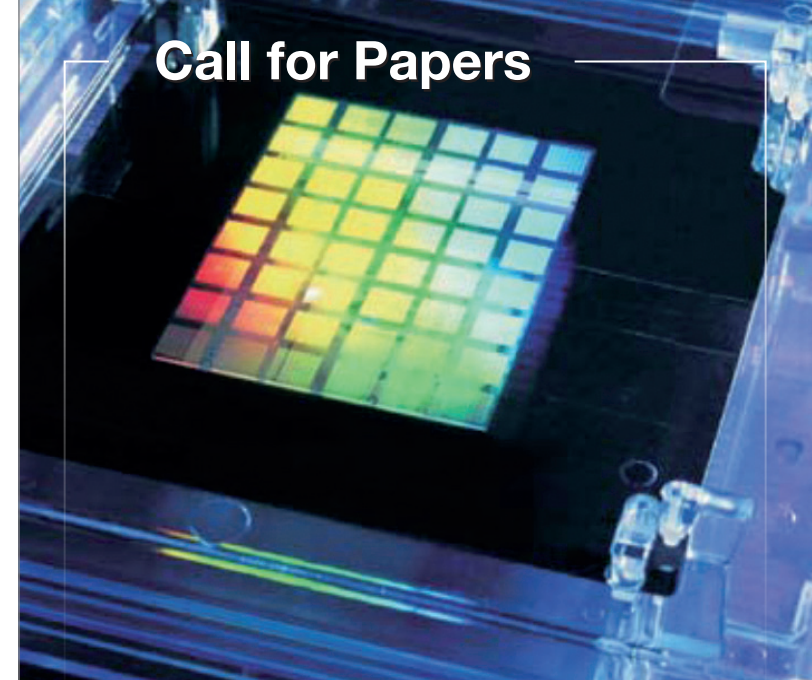
The EMLC 2022 International Program Committee

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Finders Jo, ASML, Veldhoven, The Netherlands
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Pain, Laurent, CEA-LETI, Grenoble, France
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Zurbrick, Larry, Keysight Technologies, Santa Clara, CA, USA

Cover picture:
Courtesy of Toppan Photomasks



Call for Papers

The 37th European Mask and Lithography Conference

EMLC 2022

June 20 – 23, 2022
KU Leuven, Belgium

www.emlc-conference.com



The VDE/VDI-Society Microelectronics, Microsystems and Precision Engineering (GMM) and UBC Microelectronics in cooperation with BACUS, PMJ, SEMI-Europe, and SPIE, are pleased to announce the

37th European Mask and Lithography Conference, EMLC 2022 at the KU University in Leuven, Belgium June 20th - June 22nd, 2022

and optional visit at IMEC on June 23rd, 2022

The focus of this 3 days conference is state-of-the-art of mask technology and lithography, such as mask manufacturing, mask business, lithography and mask applications, emerging mask & lithography technologies, and mask & lithography equipment.

This conference has annually brought together scientists, researchers, engineers and developers from around the world to present papers at the forefront of research, manufacturing and application. It provides a place where both specialists from industry and advanced research as well as equipment and software providers become acquainted with new developments and results.

Conference Schedule

The conference will be opened on Monday afternoon of June 20th, 2022 with a Tutorial at 02:00 PM and a Get Together and a Poster Session at 06:30 PM. On Tuesday, June 21st 2022 the conference will be continued at 09:00 AM and will close on Wednesday, June 22nd, 2022, at 6:30 PM.

The conference dinner will be held at the Faculty Club in Leuven on Tuesday evening.

Technical Exhibition

On Tuesday and Wednesday (June 21st and 22nd 2022) there will be a technical exhibition with booth space for about 20 exhibitors. Presentation tables and pin boards will be available. To be part of this Technical Exhibition, please return **the enclosed registration** form to the Conference Exhibition Organization as soon as possible, since exhibition space is limited.

Exhibition Organization

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Abstract Information

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results reported
- Potential impact and interest to the attendees.

Therefore, we highly recommend that your abstract contains enough detail to clearly describe the content of your presentation. We recommend an abstract length of **two pages** (including figures, diagrams, formatted text) as Word and PDF.

Commercial papers, papers with no new research/development content, and papers where significant information is missing will not be accepted.

In order to submit your abstract to SPIE, please open the website www.emlc-conference.com

Deadline for Abstracts: Friday, April 15th, 2022

By submitting an abstract you agree to:

- present your work in person at the conference
- and to submit a manuscript and/or your presentation materials in time.

Authors will be notified of the acceptance of their submissions by **Friday, May 6th 2022**; further manuscript format and layout instructions will be provided at that time.

Please note that we plan to have oral and poster presentations.

Deadline for submission your manuscripts to SPIE: June 30th, 2022.

Authors whose abstracts are accepted for presentation at the EMLC 2022 Conference will be asked by SPIE to provide a manuscript for publication in the SPIE Proceedings (published in the SPIE Digital Library).

PDF files of presentation materials, submitted by **June 30th, 2022** to VDE/VDI-GMM (gmm@vde.com) will be made available to the participants of the conference.

For further information concerning the submission procedure, please visit our homepage www.emlc-conference.com

Important dates

Deadlines

- Submission of abstracts.....April 15th, 2022
- Notification of authors.....May 06th, 2022
- Submission of manuscripts to SPIEJune 30th, 2022
- Submission of presentation material.....June 30th, 2022

Conference Topics

Mask Manufacturing and Mask Business

- Mask Data Preparation
- Pattern Generation: Writing, Etch, etc., including multi-beam mask writing
- Photomask Processes & Materials
- Metrology Tools & Technologies
- Defect Inspection & Repair
- Cleaning & Haze
- Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Photomasks for RET (OPC, ILT) ; PSM
- Mask Business and Management
- Mask Cost and Mask Development Strategy
- Future Mask Demand

Lithographic Systems and Processes

- Optical Resolution Enhancements including OPC, Free-form Illumination, Source-Mask-optimization (SMO) and Inverse Lithography Technology (ILT)
- Material-and Process driven Resolution Enhancements including Multiple Patterning and Chemical Shrinking
- Immersion Lithography including Defectivity
- Lithography Process Control
- Lithography and Etch Simulation including rigorous physical/chemical Models and Compact Models

Emerging Mask and Lithography Technologies

- EUV-Lithography including Masks, Materials Processes and Infrastructure.
- Directed Self-Assembly (DSA) including High Chi Materials, Defectivity Control, and new Processes
- Direct Write / Maskless Technologies including Multi-Beam Technologies
- Nano-Imprint Lithography (NIL), Soft Lithography, and Microprinting

Emerging Applications

- Non-IC Applications including Si-Photonics, flat Panel Displays and MEMS
- Lithographic Systems for non-IC Applications, including Laser Direct Write, Interference Lithography, and Mask Aligners